

THICK FILM HEATER INTEGRATED WITH LOW TEMPERATURE COMPONENTS AND METHOD OF MAKING THE SAME

Abstract of Disclosure

A thick film heater is shown wherein the thick film resistive circuit, as the heating element, is applied directly to a target object to be heated for very low temperature applications. The thick film used is polymer-based (preferably epoxy). The thick film resistive circuit is applied using conventional means. However, it is cured at higher temperatures and longer cycles than conventional thick film circuits, and preferably in multiple stages.

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